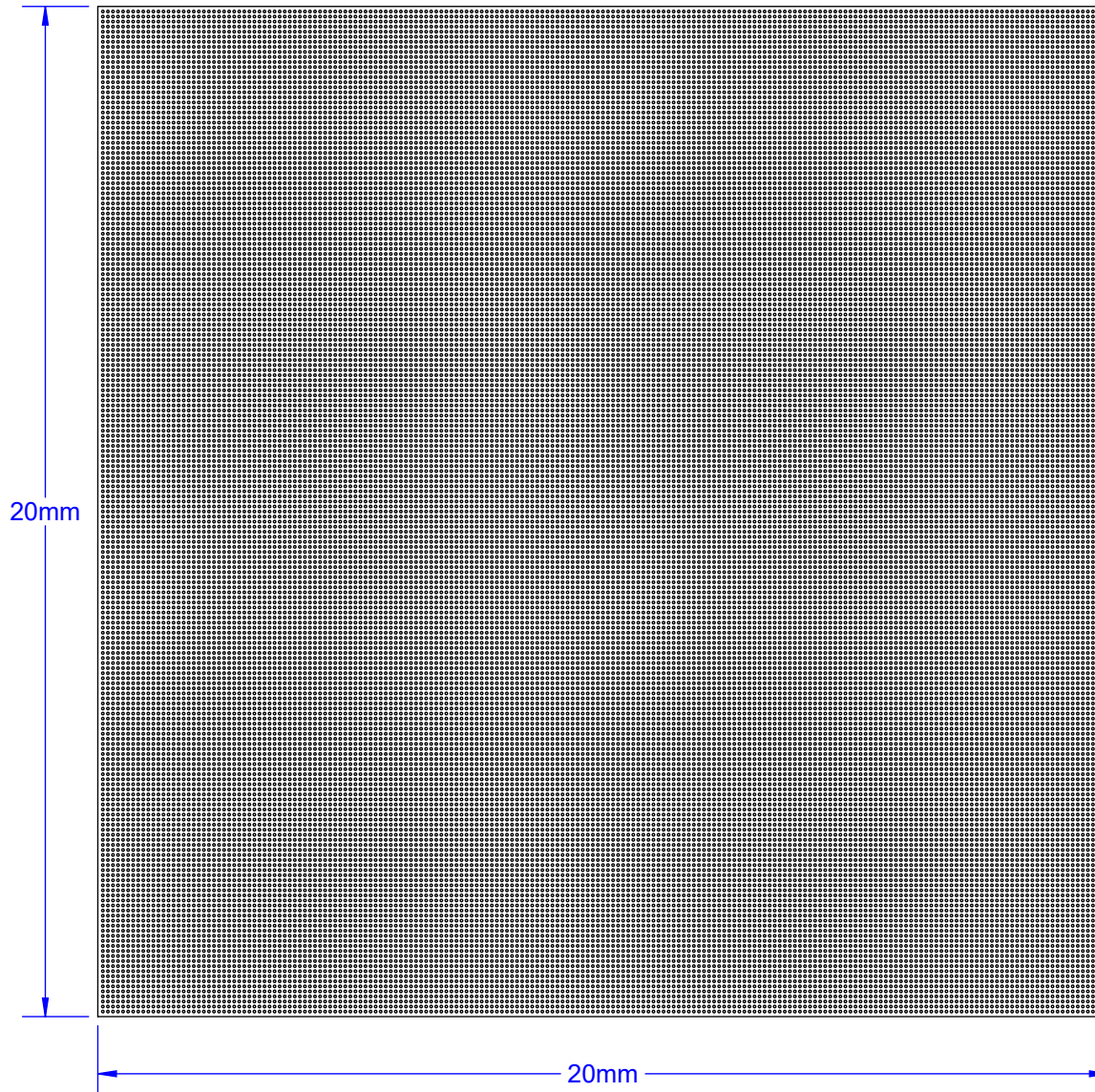
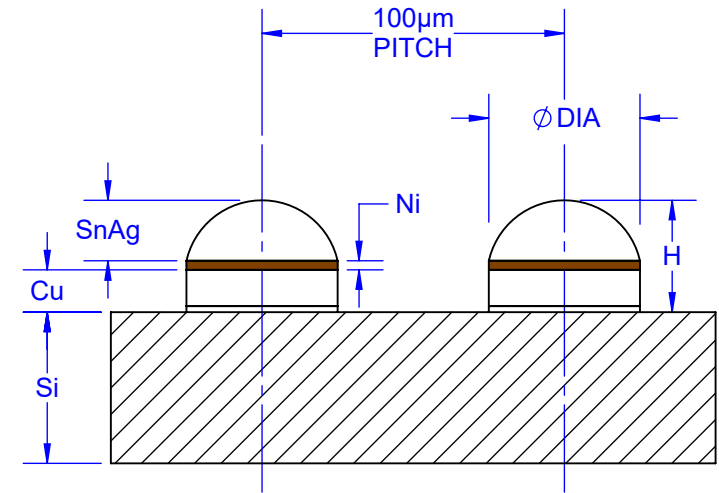


**TOP VIEW**  
**BUMP ARRAY 199 x 199**



DICING STREET 20 x 20mm  
DIE SIZE AFTER DICING ~19.96 x 19.96mm  
BUMPS ~39,601 - YIELD NOT 100%



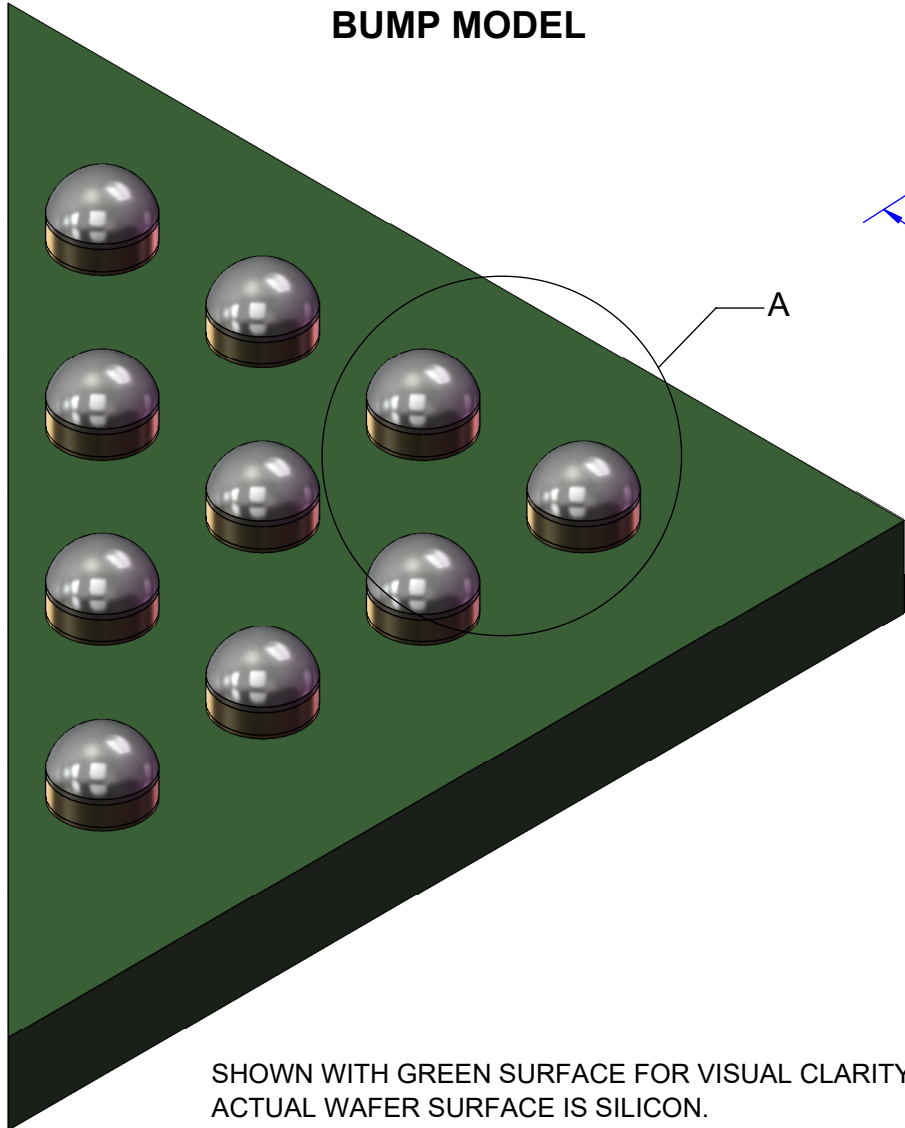
**BUMP SECTION VIEW**

BUMP DIMENSIONS TABLE		
H	BUMP HEIGHT	37µm
SnAg	SOLDER CAP	20µm
Ni	NICKEL	3µm
Cu	COPPER	14µm
Ø	DIAMETER	50µm
PITCH	BUMP PITCH	100µm

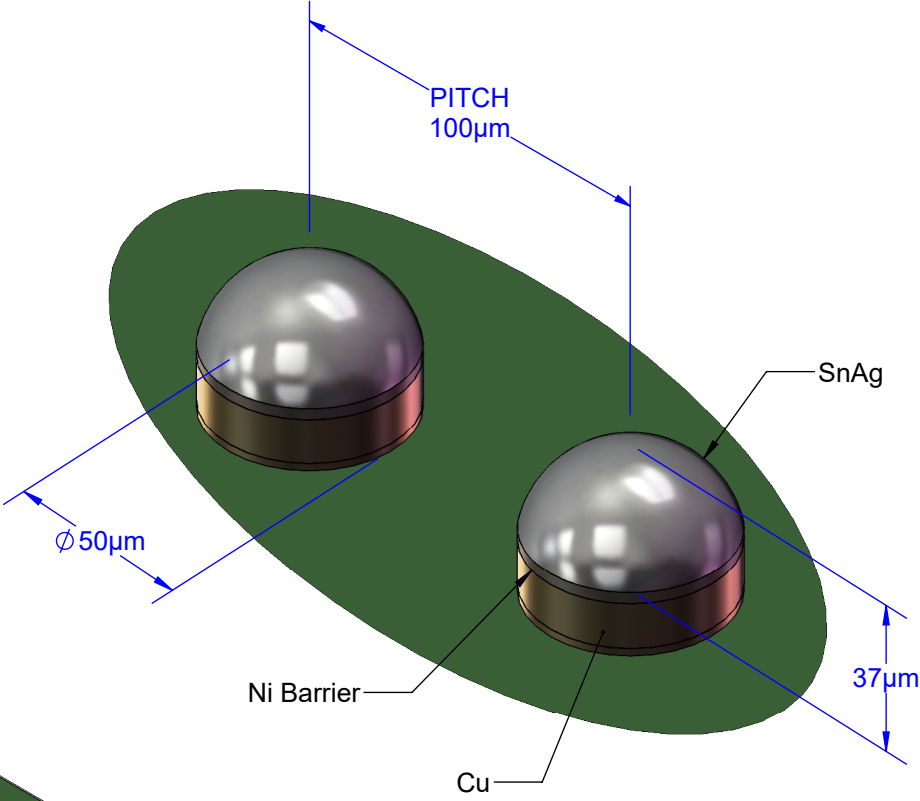
**SOLDER CAP MATERIAL: Sn98.2 Ag1.8**

APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T. Au	3/11/2023				
ENG M. Hart	3/11/2023	TITLE FC39601 - PITCH 100UM CU PILLAR 20X20MM			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		7:1	A	311990	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

**BUMP MODEL**



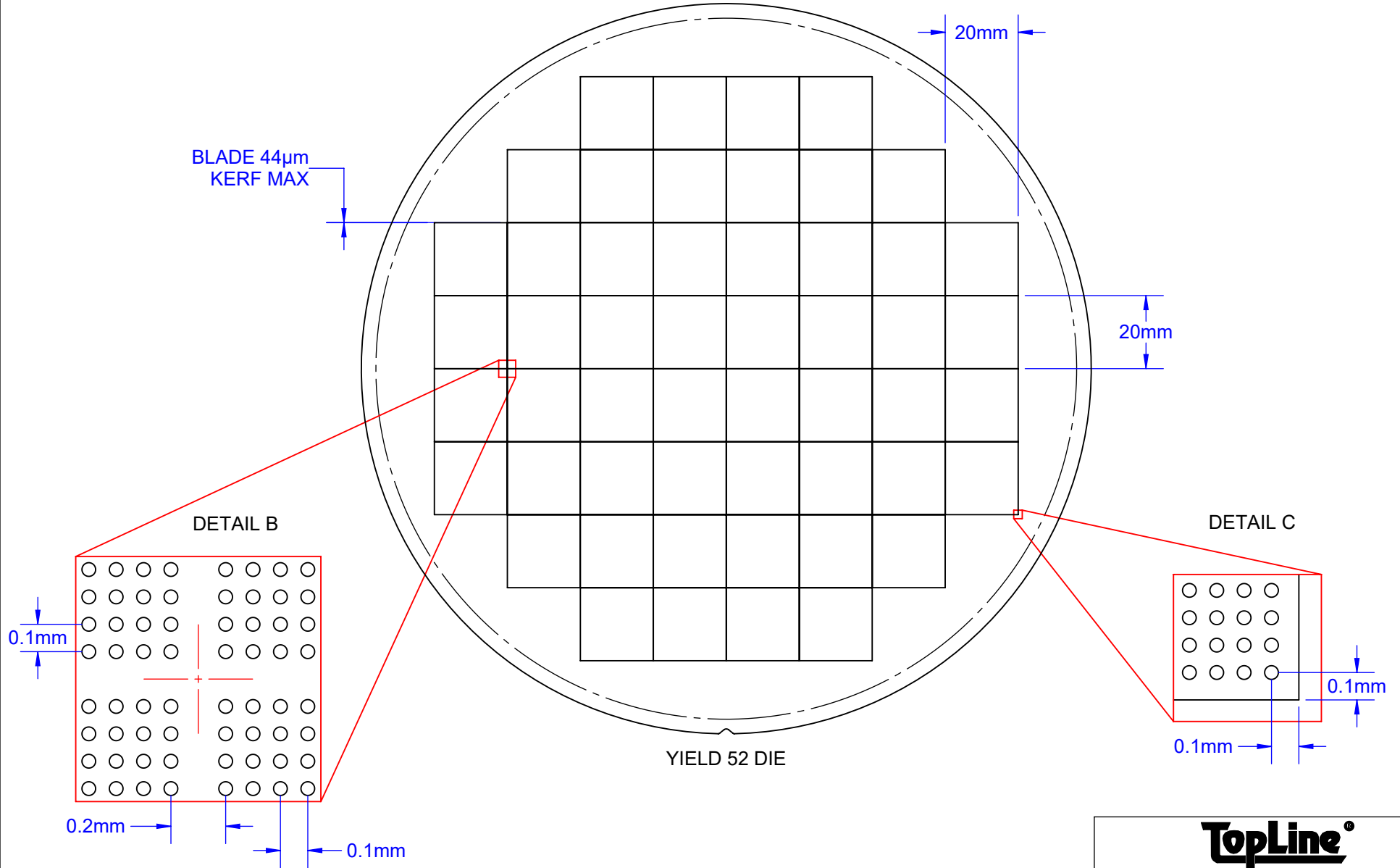
SHOWN WITH GREEN SURFACE FOR VISUAL CLARITY.  
ACTUAL WAFER SURFACE IS SILICON.



DETAIL A  
SCALE 600 : 1

<b>TopLine<sup>®</sup></b>			
TITLE FC39601 - PITCH 100UM CU PILLAR 20X20MM			
SCALE 300:1	SIZE A	DRAWING NO. 311990	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 5	

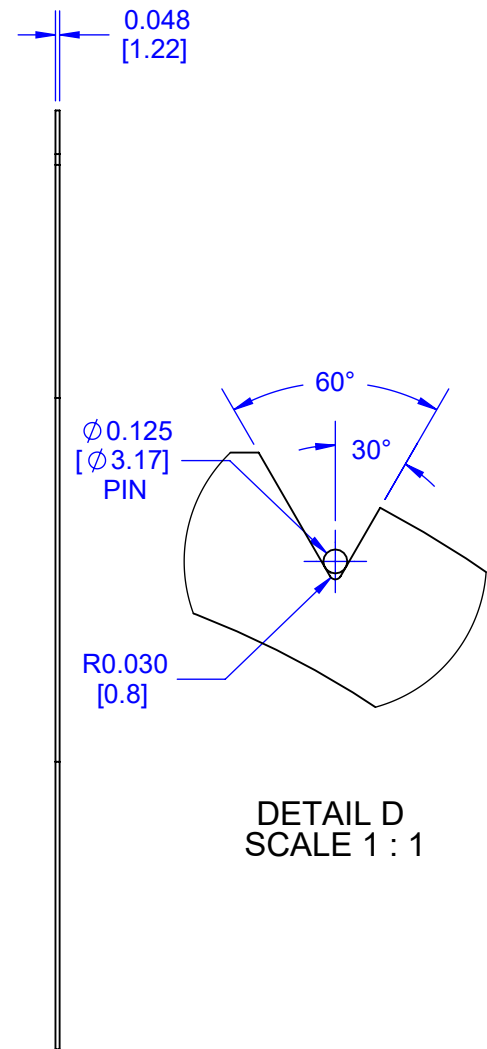
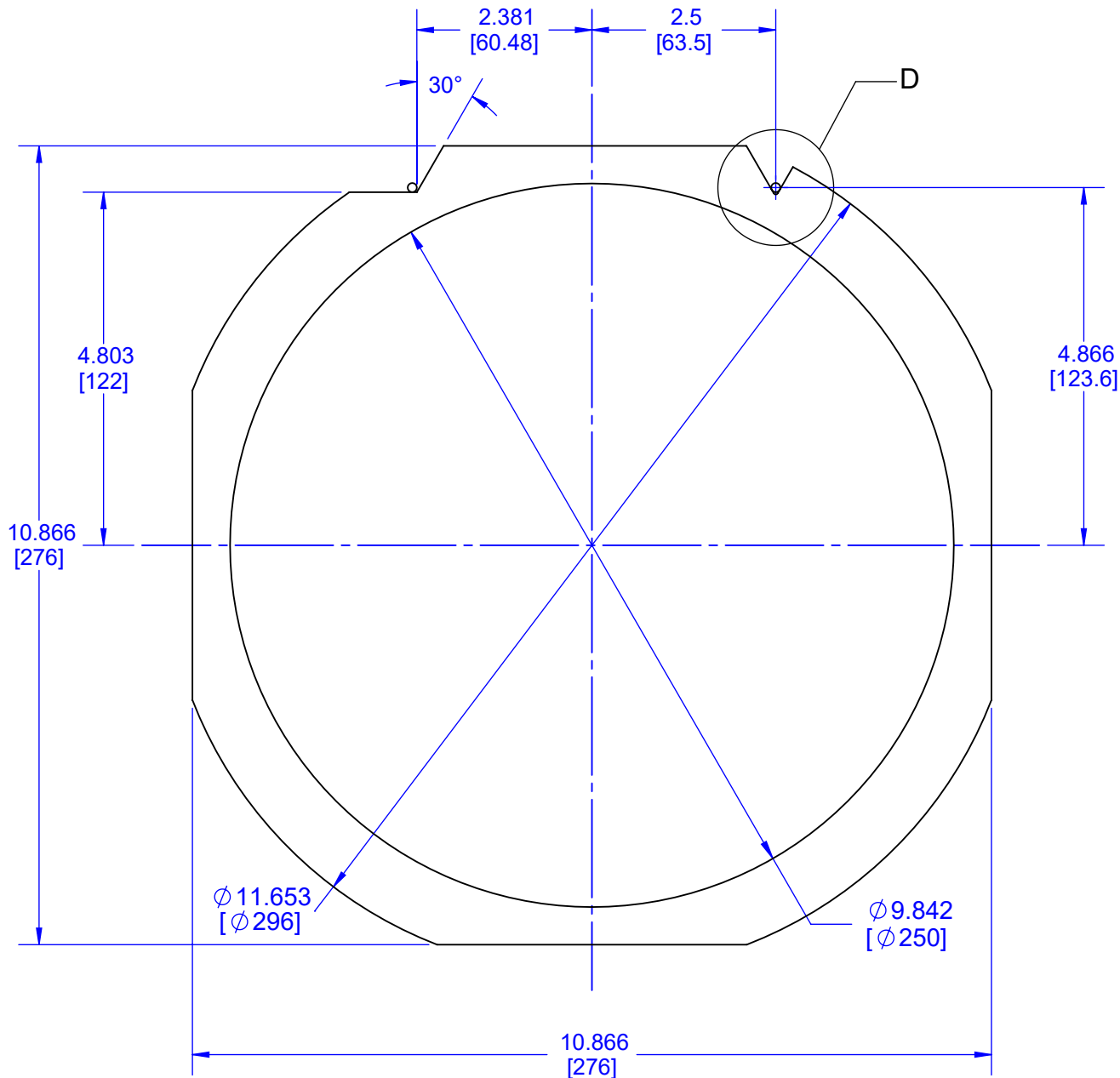
# 200mm WAFER DICING STREETS



## NOTES:

1. DISCO WAFER RING MDTFR200-4 or EQUAL.
2. UV TAPE LINTEC Adwill D-174 or EQUAL.
3. WAFER THICKNESS: 725µm BEFORE BACKGRINDING

<b>TopLine®</b>			
TITLE FC39601 - PITCH 100UM CU PILLAR 20X20MM			
SCALE 2:3	SIZE A	DRAWING NO. 311990	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 5	



DETAIL D  
SCALE 1 : 1

Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS INCHES [MM].
- 2) MATERIAL: STAINLESS STEEL.
- 3) REFERENCE FF-108 (DISCO DTF-2-8-1).

<b>TopLine®</b>			
TITLE    WAFER FRAME FF-108 8-INCH 200MM (DISCO DTF-2-8-1)			
SCALE	SIZE	DRAWING NO.	REV
4.5:10	A	190808	A
DO NOT SCALE DRAWING			SHEET 4 OF 5

**FC**

**39K**

**FLIP CHIP**

FC = FLIP CHIP (DICED)  
FCWN = UNSAWN WAFER

**BUMPS**

<u>CODE</u>	<u>BUMPS</u>	<u>ARRAY</u>
39K	39601	199 x 199

**20**

**C**

**DIE SIZE**

<u>CODE</u>	<u>MM</u>
20	20 X 20mm

**BUMP MATERIAL**

Cu PILLAR

<u>MATL</u>	<u>THICK</u>
Sn98.2 Ag1.8	20µm
Ni	3µm
Cu	14µm

**100 - OPTION**

**I**

**G**

**PITCH**

100 = 100µm

**THICKNESS**

<u>CODE</u>	<u>µm</u>	<u>MIL</u>
NONE	725µm	28.5 MIL
BG675	675µm	26.5 MIL
BG500	500µm	20 MIL
BG400	400µm	16 MIL
BG375	375µm	15 MIL
BG300	300µm	12 MIL
BG250	250µm	10 MIL
BG200	200µm	8 MIL
BG150	150µm	6 MIL
BG100	100µm	4 MIL
BG50	50µm	2 MIL

OTHER THICKNESS AVAILABLE

**\* CIRCUIT**

I = ISOLATED  
BUS = ALL SHORTED

**PACKAGING**

G = GEL PAK (4 pcs)  
P = 4" CHIP TRAY (9 pcs)  
UV = TAPE RING  
C = CASSETTE

OTHER AVAILABLE

**\* CIRCUIT NOTES:**

ISOLATED = SiO<sub>2</sub> STANDARD  
BUS = WAFER PROBE ONLY



TITLE				FC39601 - PITCH 100UM CU PILLAR 20X20MM			
SCALE	SIZE	DRAWING NO.		REV			
NONE	A	311990		A			
DO NOT SCALE DRAWING						SHEET 5 OF 5	